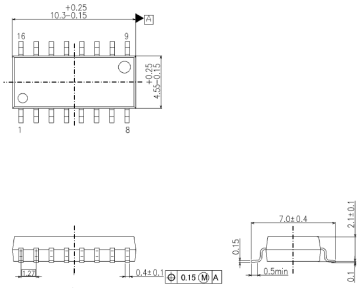
TOSHIBA PHOTOCOUPLER InGaAs IRED & PHOTO-TRANSISTOR

TLP292-4

Programmable Controllers
Switching Power Supplies
Simplex/Multiplex Data Transmissions

Unit in mm



TOSHIBA 11-11F1

Weight: 0.19 g (typ.)

TLP292-4 consists of phototransistors optically coupled to two InGaAs infrared emitting diodes connected inverse parallel, and can operate directly by AC input current.
TLP292-4 is housed in the very small and thin SO16 package.
Since TLP292-4 is guaranteed wide operating temperature (Ta=-55 to 125 ˚C) and high isolation voltage (3750Vrms), it is suitable for high-density surface mount applications such as programmable controllers.

- Collector-Emitter Voltage : 80 V (min)
- Current Transfer Ratio : 50% (min)
  Rank GB: 100 %(min)
- Isolation Voltage : 3750 Vrms (min)
- Operation temperature range: -55 to 125 ˚C
- Safety standards

  UL- approved: UL1577, File No. E67349

  cUL- approved: CSA Component Acceptance Service No.5A, File No. E67349

  CQC- approved : GB4943-1, GB8898

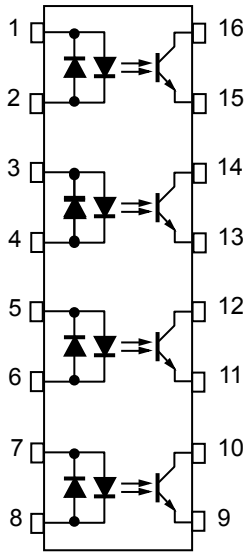
  仅适用于海拔 2000m 以下地区安全使用

  VDE-under application : EN60747-5-5 (Note), approved No. 40009347

  Note : When an EN60747-5-5 approved type is needed, please designate the Option (V4).

Pin Configuration

TLP292-4



1,3,5,7 :Cathode, Anode
2,4,6,8 :Anode, Cathode
9,11,13,15 :Emitter
10,12,14,16 :Collector

Construction Mechanical Rating

Creepage Distance	5.0 mm (min)
Clearance	5.0 mm (min)
Internal isolation thickness	0.4 mm (min)

Start of commercial production
2014-04

Current Transfer Ratio (Unless otherwise specified, Ta=25°C)

Rank (Note1)	Test condition	Current Transfer Ratio (%) I_C / I_F		Marking of Classification
		Min	Max	
Blank	I_F =±5 mA, V_{CE} = 5 V	50	600	Brank
GB		100	600	GB
LA (Note2)	I_F =±0.5 mA, V_{CE} = 5 V	50	600	LA
LGB (Note2)		100	600	LB

Note 1: Specify both the part number and a rank in this format when ordering.

Example: rank GB: TLP292-4(GB,E

For safety standard certification, however, specify the part number alone.
TLP292−4 (GB,E: TLP292-4

Note2: The LA and LGB rank are made CTR rank of the low input current condition.

Absolute Maximum Ratings (Note)(Unless otherwise specified, Ta = 25°C)

	Characteristics	Symbol	Note	Rating	Unit
LED	R.M.S. forward current	$I_{F(RMS)}$		±50	mA
	Input forward current derating (Ta≥50°C)	$\Delta I_F / \Delta Ta$		−0.59	mA /°C
	Input forward current(Pulsed)	I_{FP}	(Note2)	±1	A
	LED power disipation	P_D		70	mW
	LED power dissipation derating(Ta≥50°C)	$\Delta P_D / \Delta Ta$		-0.82	mW /°C
	Junction temperature	T_j		125	°C
DETECTOR	Collector-emitter voltage	V_{CEO}		80	V
	Emitter-collector voltage	V_{ECO}		7	V
	Collector current	I_C		50	mA
	Collector power dissipation (1 Circuit)	P_C		100	mW
	Collector power dissipation derating(Ta≥25°C) (1 Circuit)	$\Delta P_C / \Delta Ta$		-0.91	mW /°C
	Junction temperature	T_j		125	°C
COMMON	Operating temperature range	T_{opr}		−55 to 125	°C
	Storage temperature range	T_{stg}		−55 to 125	°C
	Lead soldering temperature	T_{sol}		260 (10s)	°C
	Total power dissipation (1 Circuit)	P_T		170	mW
	Input power dissipation derating (Ta≥25°C) (1 Circuit)	$\Delta P_T / \Delta Ta$		−1.55	mW /°C
	Isolation Voltage AC, 60s, R.H.≤60%	BV_S	(Note3)	3750	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook (“Handling Precautions”/“Derating Concept and Methods”) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note2: Pulse width ≤ 100μs, frequency 100Hz

Note3: This device is considered as a two-terminal device: Pins 1, 2, 3, 4, 5, 6, 7 and 8 are shorted together, and pins 9, 10, 11, 12, 13, 14, 15 and 16 are shorted together.

Electrical Characteristics (Unless otherwise specified, Ta = 25°C)

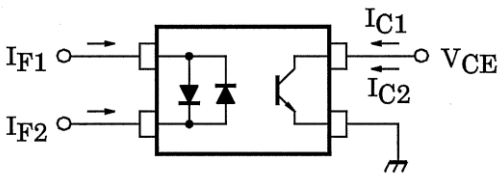
	CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
LED	Input forward voltage	V_F	I_F = ±10 mA	1.1	1.25	1.4	V
	Input capacitance	C_T	V = 0 V, f = 1 MHz	—	60	—	pF
DETECTOR	Collector-emitter breakdown voltage	$V_{(BR)\ CEO}$	I_C = 0.5 mA	80	—	—	V
	Emitter-collector breakdown voltage	$V_{(BR)\ ECO}$	I_E = 0.1 mA	7	—	—	V
	Dark current	I_{DARK}	V_{CE} = 48 V,	—	0.01	0.08	μA
			V_{CE} = 48 V, Ta = 85°C	—	2	50	μA
	Collector-emitter capacitance	C_{CE}	V = 0 V, f = 1 MHz	—	10	—	pF

Coupled Electrical Characteristics (Unless otherwise specified, Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
Current transfer ratio	I_C / I_F	I_F = ±5 mA, V_{CE} = 5 V	50	—	600	%
		Rank GB	100	—	600	
Saturated current transfer ratio	I_C / $I_{F\ (sat)}$	I_F = ±1 mA, V_{CE} = 0.4 V	—	60	—	%
		Rank GB	30	—	—	
Collector-emitter saturation voltage	$V_{CE\ (sat)}$	I_C = 2.4 mA, I_F = ±8 mA	—	—	0.3	V
		I_C = 0.2 mA, I_F = ±1 mA	—	0.2	—	
		Rank GB	—	—	0.3	
Off-state collector current	$I_{C\ (off)}$	V_F = ±0.7 V, V_{CE} = 48 V	—	—	10	μA
Collector current ratio	I_C (ratio)	I_C (I_F = −5 mA) / I_C (I_F = 5 mA) See Fig 1	0.33	—	3	—

Fig.1 Collector current ratio test circuit

$$I_{C(ratio)} = \frac{I_{C2}(I_F = I_{F2}, V_{CE} = 5V)}{I_{C1}(I_F = I_{F1}, V_{CE} = 5V)}$$



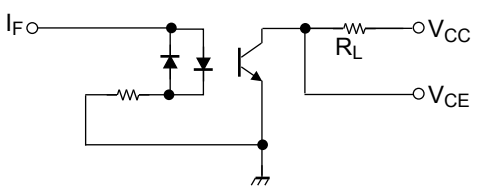
Isolation Characteristics (Unless otherwise specified, Ta = 25°C)

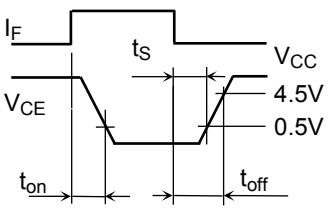
CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
Total capacitance (input to output)	C_S	V_S = 0 V, f = 1 MHz	—	0.8	—	pF
Isolation resistance	R_S	V_S = 500 V, R.H.≤60%	1×10^{12}	10^{14}	—	Ω
Isolation voltage	BV_S	AC , 60 s	3750	—	—	Vrms
		AC , 1 s in OIL	—	10000	—	
		DC , 60 s in OIL	—	10000	—	Vdc

Switching Characteristics (Unless otherwise specified, Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
Rise time	t_r	V_{CC} = 10 V, I_C = 2 mA R_L = 100Ω	—	2	—	μs
Fall time	t_f		—	3	—	
Turn-on time	t_{on}		—	3	—	
Turn-off time	t_{off}		—	3	—	
Turn-on time	t_{on}	R_L = 1.9 kΩ (Fig.2) V_{CC} = 5 V, I_F = 16 mA	—	1.5	—	μs
Storage time	t_s		—	20	—	
Turn-off time	t_{off}		—	35	—	

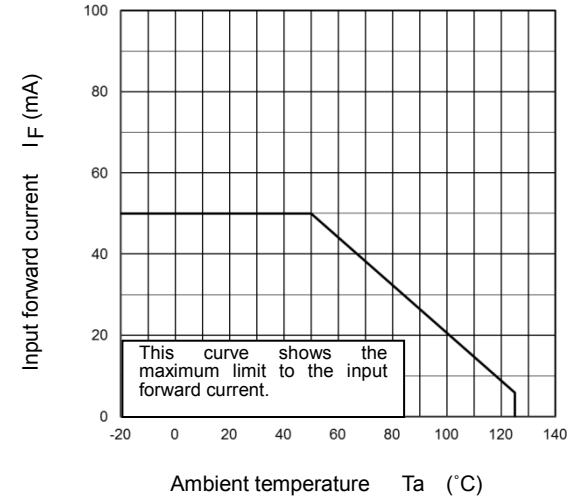
(Fig.2) Switching Time Test Circuit



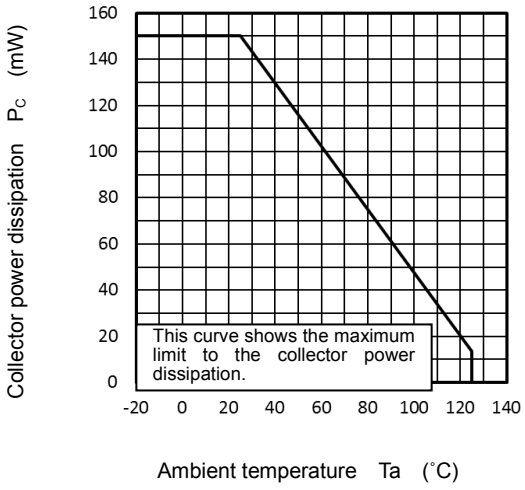


Characteristics Curves (Note)

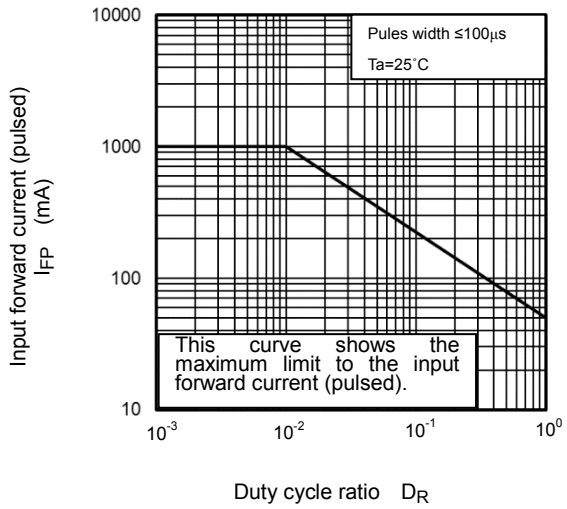
I_F - Ta



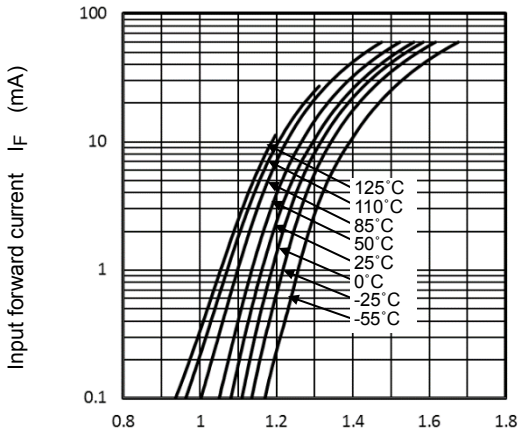
P_C - Ta



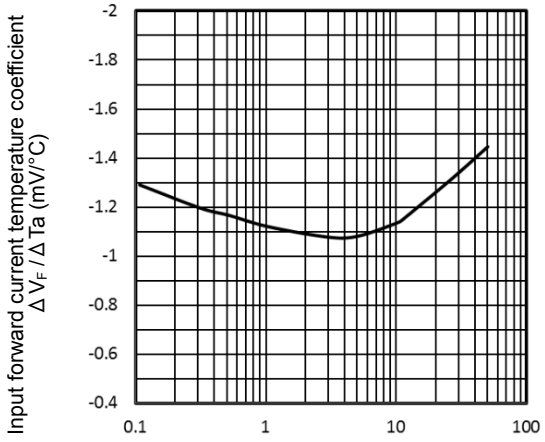
I_{FP} - D_R



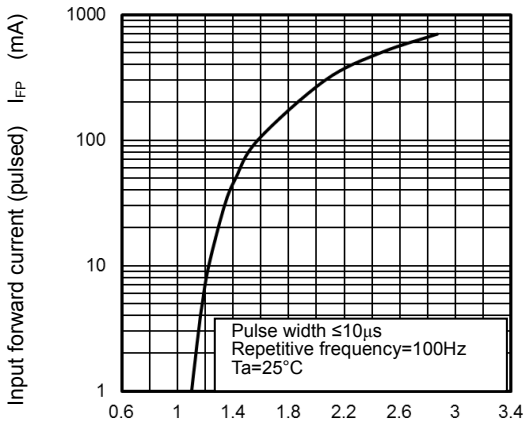
I_F - V_F



$\Delta V_F / \Delta Ta$ - I_F

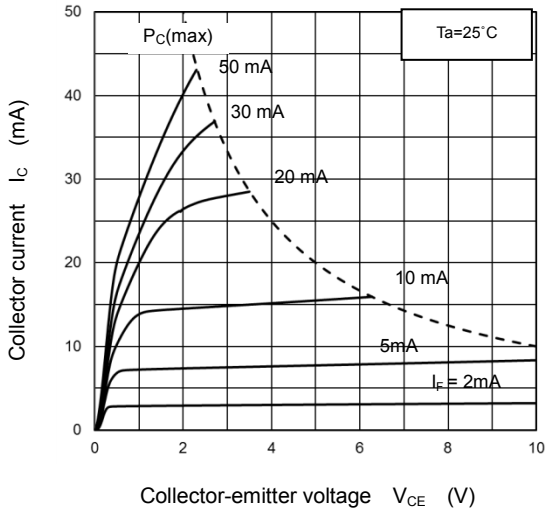


I_{FP} – V_{FP}

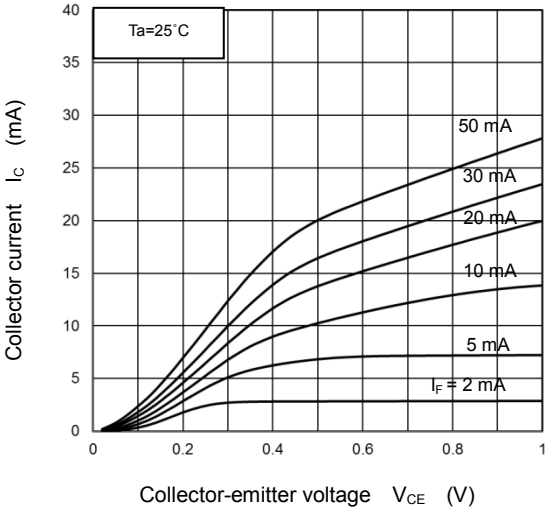


Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

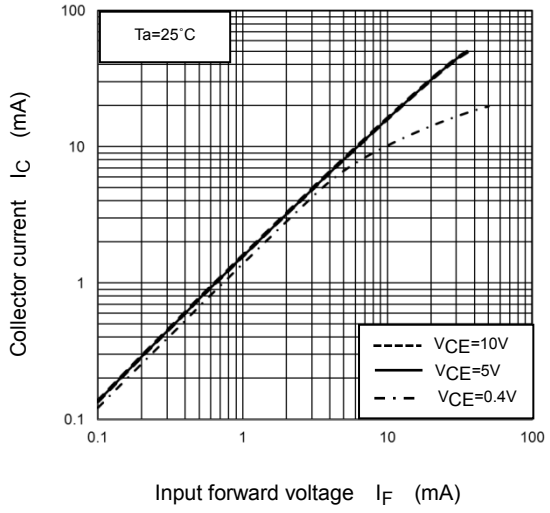
I_C-V_{CE}



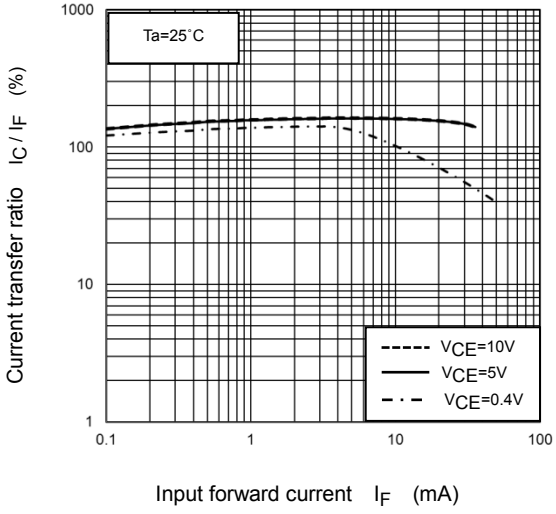
I_C-V_{CE}



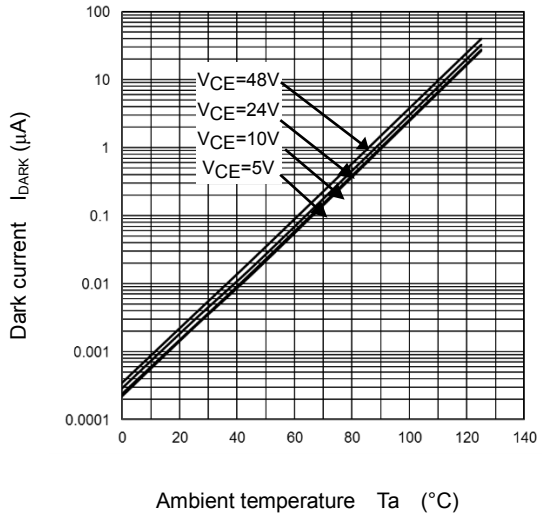
I_C-I_F



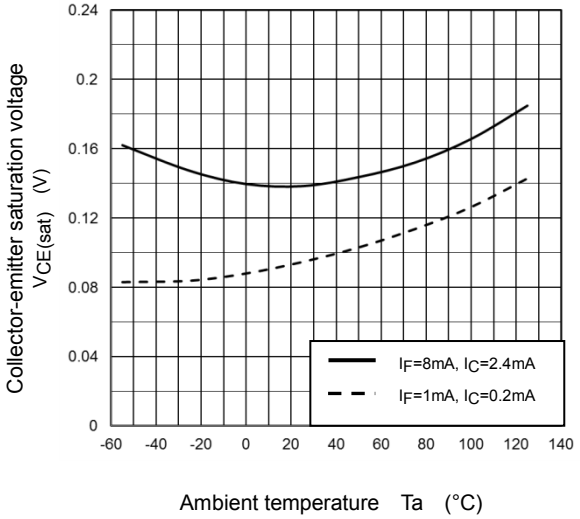
I_C/I_F - I_F



I_{DARK}-Ta



$V_{CE(sat)}$ - Ta



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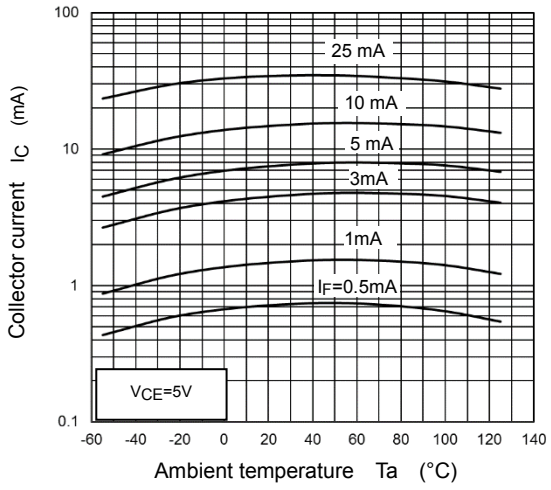
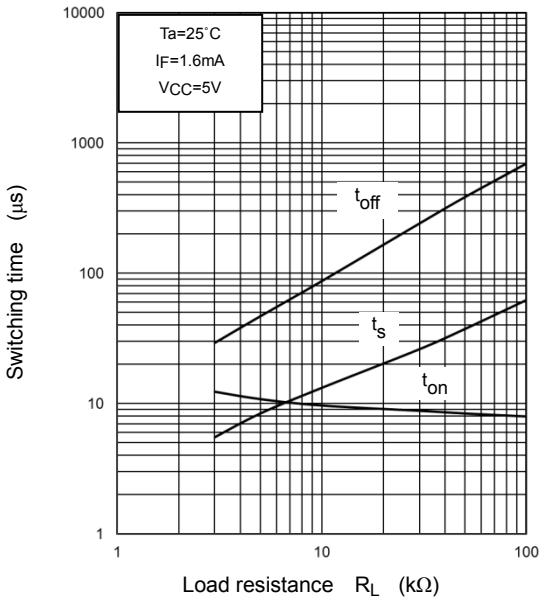
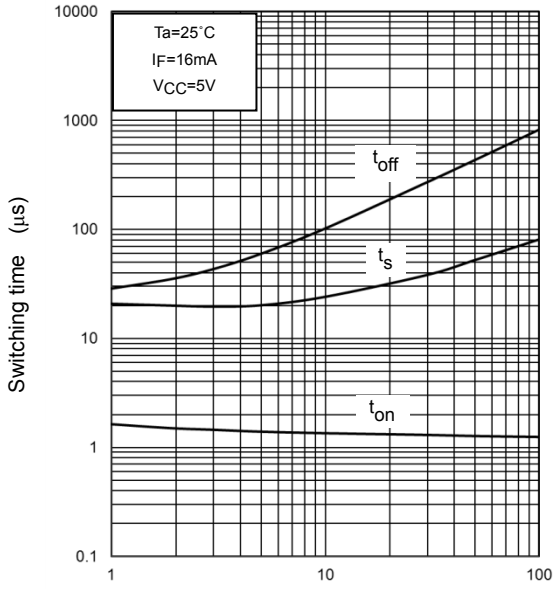
I_C - Ta



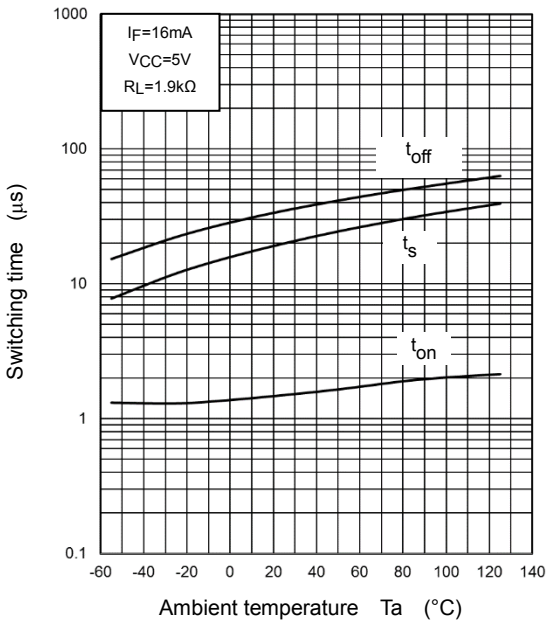
Switching time - R_L



Switching time - R_L



Switching time - Ta



Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Soldering and Storage

1. Precautions for Soldering

The soldering temperature should be controlled as closely as possible to the conditions shown below, irrespective of whether a soldering iron or a reflow soldering method is used.

- When using soldering reflow (See Fig2 and Fig3)

  Reflow soldering must be performed once or twice.

  The mounting should be completed with the interval from the first to the last mountings being 2 weeks.

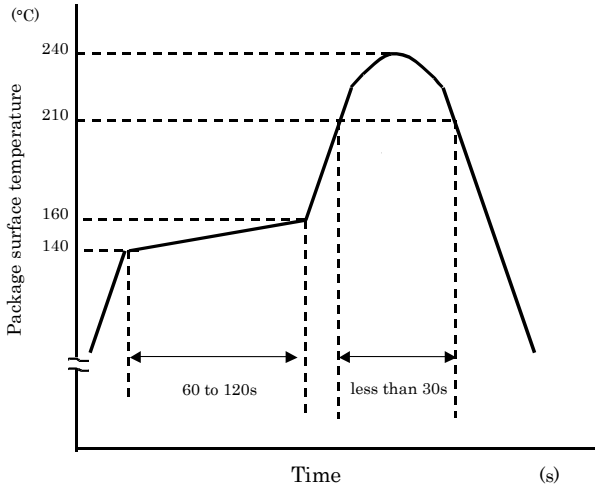


Fig2. An example of a temperature profile when Sn-Pb eutectic solder is used

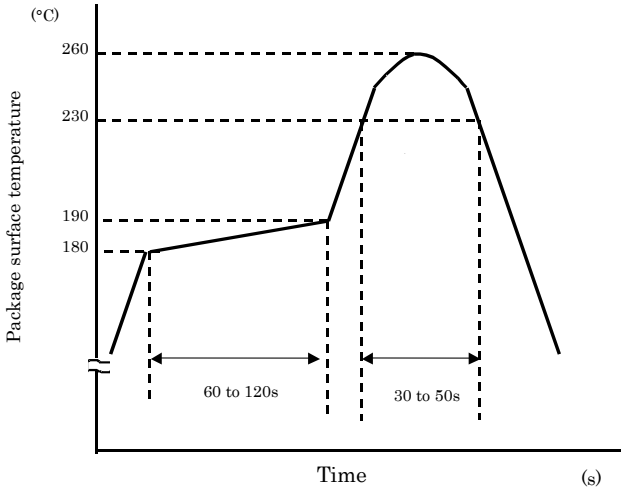


Fig 3.An example of a temperature profile when lead(Pb)-free solder is used

- When using soldering flow (Applicable to both eutectic solder and Lead(Pb)-Free solder)

  Apply preheating of 150°C for 60 to 120 seconds.

  Mounting condition of 260°C within 10 seconds is recommended.

  Flow soldering must be performed once.

- When using soldering Iron

  Complete soldering within 10 seconds for lead temperature not exceeding 260°C or within 3 seconds at not exceeding 350°C.

  Heating by soldering iron must be done only once per lead.

2. Precautions for General Storage

1) Avoid storage locations where devices may be exposed to moisture or direct sunlight.
2) Follow the precautions printed on the packing label of the device for transportation and storage.
3) Keep the storage location temperature and humidity within a range of 5°C to 35°C and 45% to 75%, respectively.
4) Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
5) Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
6) When restoring devices after removal from their packing, use anti-static containers.
7) Do not allow loads to be applied directly to devices while they are in storage.
8) If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.

Option: Specification for Embossed-Tape Packing (TP) for Mini-Flat Coupler

1. Applicable Package

Package Name	Product Type
SO16	Mini-Flat Coupler

2. Product Naming System

Type of package used for shipment is denoted by a symbol suffix after a product number. The method of classification is as below.

Example) TLP292-4(GB-TP,E

Part number: TLP292-4
CTR rank: GB
Tape type: TP
[[G]]/RoHS COMPATIBLE: E (Note)

Note : Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product.
The RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 Jun 2011 on the restriction of the use of certain hazardous substances in electrical and electronics equipment.

3. Tape Dimensions Specification

3.1 Orientation of Device in Relation to Direction of Tape Movement

Device orientation in the recesses is as shown in Figure 3.1.1.

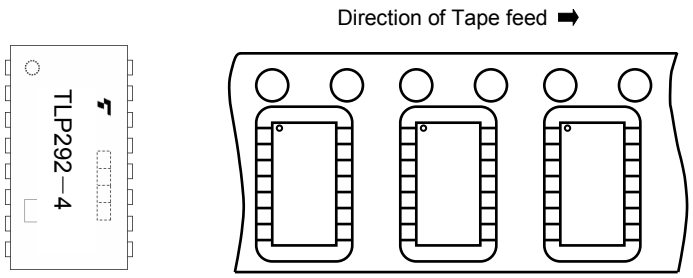


Figure3.1.1 Device Orientation

3.2 Packing Quantity

2000 pcs per reel

3.3 Empty Device Recesses are as Shown in Table 1.

Table 1 Empty Device Recesses

	Standard	Remarks
Occurrences of 2 or more successive empty device recesses	0	Within any given 40-mm section of tape, not including leader and trailer
Single empty device recesses	6 device (max) per reel	Not including leader and trailer

3.4 Tape Leader and Trailer

The start end of the tape has 50 or more empty cavities. The hub end of the tape has 50 or more empty cavities and two empty turns only for a cover tape.

3.5 Tape Dimensions

Tape material: Plastic (protection against electrostatics)

(1) Figure3.5.1 Tape Forms

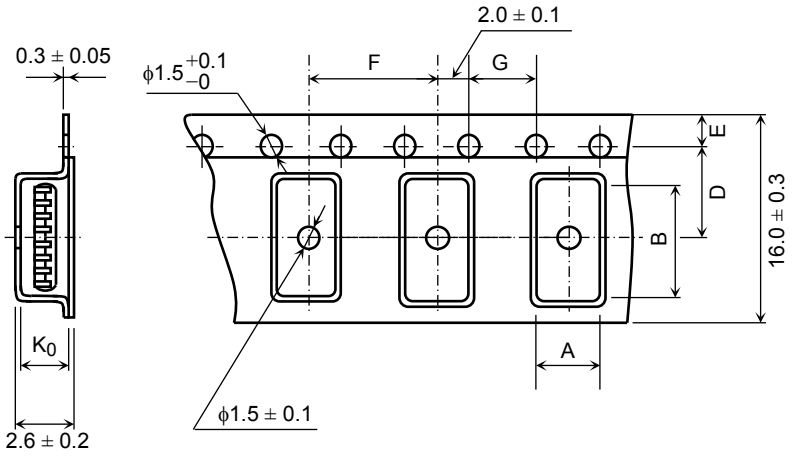


Table 3.5.1 Tape Dimensions

Unit: mm
unless otherwise specified: ±0.1

Symbol	Dimension	Remark
A	7.5	—
B	10.5	—
D	7.5	Center line of indented square hole and sprocket hole
E	1.75	Distance between tape edge and hole center
F	12.0	Cumulative error +0.1/-0.3 (max) per 10 feed holes
G	4.0	Cumulative error +0.1/-0.3 (max) per 10 feed holes
K_0	2.2	Internal space

3.6 Reel specification

Material: Plastic

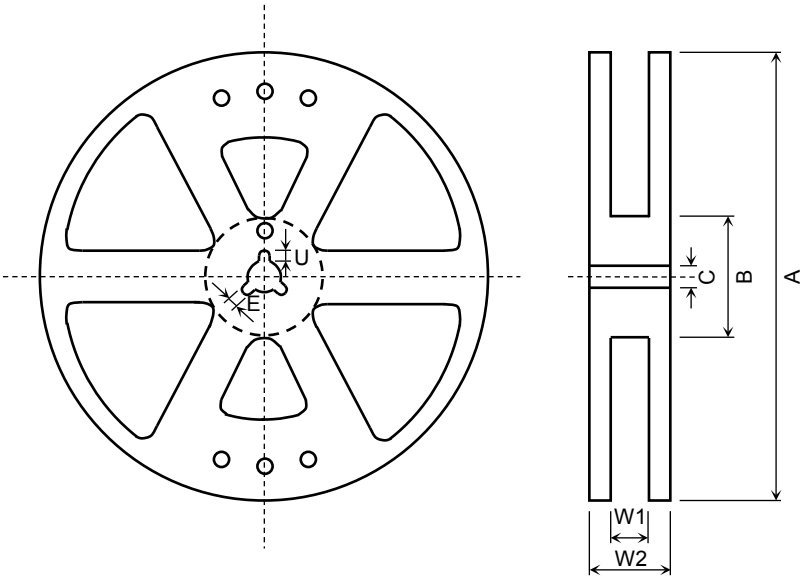


Table 3.6.1 Reel Dimensions

Unit: mm

Symbol	Dimension
A	ϕ330 ± 2
B	ϕ80 ± 1
C	ϕ13 ± 0.5
E	2.0 ± 0.5
U	4.0 ± 0.5
W1	17.5 ± 0.5
W2	21.5 ± 1.0

Figure 3.6.1 Reel Dimensions

4. Packing

Either one reel or ten reels (maximum) of photocouplers are packed in a shipping carton.

5. Label Format

The label on each carton provides the part number, quantity, lot number, the Toshiba logo, CTR rank, etc.

6. Ordering Information

When placing an order, please specify the part number, CTR rank, tape type and quantity (must be a multiple of 2000) as shown in the following example.

Example) TLP292-4(GB-TP,E 2000 Pcs

Part number: TLP292-4
CTR rank (GB
Tape type: TP
[[G]]/RoHS COMPATIBLE: E (Note)
Quantity (must be a multiple of 2000): 2000 Pcs

Note : Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product.
The RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 Jun 2011 on the restriction of the use of certain hazardous substances in electrical and electronics equipment.

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